

Amendments to the Claims

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Claims 1-3 (cancelled)

4. (previously presented) The cleaning wipe of Claim 23 wherein the acetylenic diol is present in the range of 0.01% to 0.3% by weight.

5. (previously presented) The cleaning wipe of Claim 4 wherein the acetylenic diol is present in the range of 0.05% to 0.2% by weight.

6. (previously presented) The cleaning wipe of Claim 5 wherein the acetylenic diol has a vapor pressure of at least 1×10^{-4} torr at 25°C.

7. (previously presented) The cleaning wipe of Claim 6 wherein the acetylenic diol has a vapor pressure of at least 1×10^{-3} torr at 25°C.

8. (previously presented) The cleaning wipe of Claim 7 wherein the acetylenic diol is dimethyl octynediol.

9. (previously presented) The cleaning wipe of Claim 7 wherein the acetylenic diol is tetramethyl decynediol.

10. (previously presented) The cleaning wipe of Claim 4 wherein the wipe substrate is selected from the group consisting of: cotton, abaca, polyester, nylon, polyester/cellulose, rayon, polypropylene, rayon/polyester, polypropylene/cellulose, polyurethane, cotton/polyester and mixtures thereof.

11. (previously presented) The cleaning wipe of Claim 4 wherein the acetylenic diol is selected from the group consisting of: dimethyl octynediol; tetramethyl decynediol; 2,6,9,13-tetramethyl-2,12-tetradecadien-7-yne-6-9-diol; 2,6,9-trimethyl-2-decen-7-yne-6-9-diol;; 7,10-dimethyl-8-hexadecyne-7,10-diol; 2,4,7,9-tetramethyl-5-decyne-4,7-diol; 4,7-dimethyl-5-decyne-4,7-diol; 3,6-diethyl-4-octyne-3,6-diol; 2,5-dicyclopropyl-3-hexyne-2,5-diol; 2,5-diphenyl-3-hexyne-2,5-diol; 3,5-dimethyl-1-hexyn-3-ol, 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol and mixtures thereof.

12. (cancelled)

13. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a fibrous substrate.

14. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a woven fibrous substrate.

15. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a nonwoven fibrous substrate.

16. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a sponge.

17. (previously presented) The cleaning wipe of Claim 11 wherein the water is high purity water.

18. (previously presented) The cleaning wipe of Claim 11 wherein the water is deionized water.

19. (previously presented) The cleaning wipe of Claim 11 wherein the water is distilled water.

20. (previously presented) A prewetted cleaning wipe for cleaning surfaces in an electronic materials fabricating area having a low volatile organic chemical content in the range of 0.001% to 0.5% by weight and low nonvolatile residue property of at least 1×10^{-4} torr at 25°C comprising; a woven fibrous polyester/cellulose wipe substrate wetted with an aqueous solution consisting essentially of high purity water selected from the group consisting of distilled water and deionized water, and from 0.001 % to 0.5% by weight of an acetylenic diol surface active agent selected from the group consisting of dimethyl octynediol, tetramethyl decynediol and mixtures thereof.

21. (cancelled)

22. (previously presented) The cleaning wipe of Claim 20 wherein the acetylenic diol surface active agent is present in an amount from 0.05% to 0.2% by weight.

23. (previously presented) In a cleaning wipe for use in cleaning an electronics fabrication industry clean room comprising a wipe substrate wetted with a cleaning solution, the improvement which resides in a cleaning wipe having low volatile organic chemical and low nonvolatile residue properties comprising a wipe substrate wetted with a solution consisting essentially of water and from 0.001% to 0.5% by weight of an acetylenic diol.

24 (New) In a process for cleaning surfaces in an electronics fabrication cleanroom wherein the surfaces are contacted with a cleaning wipe and contaminants removed from said surfaces, the improvement which comprises:

utilizing a cleaning wipe consisting essentially of a wipe substrate impregnated with a solution consisting essentially of water and from 0.001% to 0.5% by weight of an acetylenic diol.

25. (New) The process of Claim 24 wherein the acetylenic diol is selected from the group consisting of dimethyl octynediol and tetramethyl decynediol.